

DIGITAL IMAGE CAPTURING MODULE ASSEMBLY AND METHOD OF FABRICATING THE SAME

The specification of which

(check one) _____ is attached hereto.
 _____ was filed on _____
 under Application Serial No. _____ and was
 amended on _____
 _____ (if applicable)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the Office all information which is material to Patentability as defined in 37 CFR § 1.56.

I hereby claim foreign priority benefits under 35 USC § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)

<u>APPLICATION NUMBER</u>	<u>COUNTRY</u>	<u>FILING DATE</u>
---------------------------	----------------	--------------------

I hereby claim the benefit under 35 USC §120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of 35 USC § 112, I acknowledge the duty to disclose to the Office information which is material to patentability as defined in CFR § 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

<u>APPLICATION NUMBER</u>	<u>FILING DATE</u>	<u>STATUS</u> (Patented, Pending, Abandoned)
---------------------------	--------------------	---

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

**Address all correspondence to: Mr. Peter F. Corless
EDWARDS & ANGELL, LLP
101 Federal Street,
Boston, MA 02110,
U.S.A.**

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 USC 1001, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Full name of sole or first inventor Kah-Ong TAN
 Inventor's Signature *Kah-Ong Tan* Date MAY 29, 2003
 Residence Shanghai Citizenship Malaysia
 Post Office Address INVENTEC BUILDING, 66 HOU-KANG ST.,
SHIH-LIN DISTRICT, TAIPEI, TAIWAN, R.O.C.

Full name of second inventor Hui WANG
 Inventor's Signature *Hui Wang* Date MAY 29, 2003
 Residence Shanghai Citizenship CHINA P.R.C.
 Post Office Address INVENTEC BUILDING, 66 HOU-KANG ST.,
SHIH-LIN DISTRICT, TAIPEI, TAIWAN, R.O.C.

Full name of third joint inventor, if any Dong-Jin ZHANG
 Inventor's Signature *Dong-Jin Zhang* Date MAY 29, 2003
 Residence Shanghai Citizenship CHINA P.R.C.
 Post Office Address INVENTEC BUILDING, 66 HOU-KANG ST.,
SHIH-LIN DISTRICT, TAIPEI, TAIWAN, R.O.C.

Full name of fourth joint inventor, if any Peter TAO
 Inventor's Signature *Peter TAO* Date MAY 29, 2003
 Residence Shanghai Citizenship CHINA P.R.C.
 Post Office Address INVENTEC BUILDING, 66 HOU-KANG ST.,
SHIH-LIN DISTRICT, TAIPEI, TAIWAN, R.O.C.

Full name of fifth joint inventor, if any _____
 Inventor's Signature _____ Date _____
 Residence _____ Citizenship _____
 Post Office Address _____

Full name of sixth joint inventor, if any _____
 Inventor's Signature _____ Date _____
 Residence _____ Citizenship _____
 Post Office Address _____